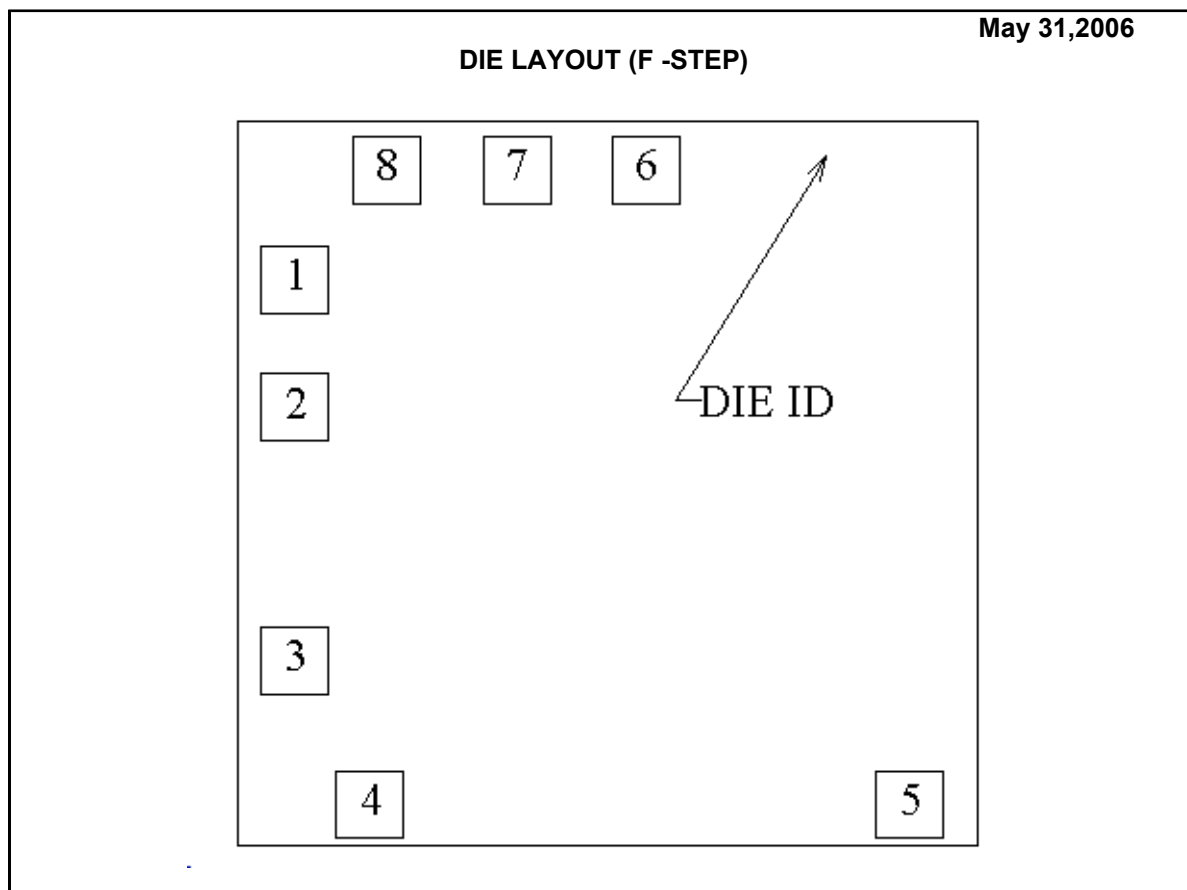


LM101A MD8 MW8
OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM101	Bond Pad Opening Size (min)	109 μ m x 109 μ m
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1168 μ m x 1194 μ m 46.0mils x 47.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	205 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (F -Step)

(Referenced to die center, coordinates in μm) **NC** = No Connection, **N.U.** = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
BALANCE COMP	1	-505	329	109	x	109
INPUT -	2	-505	123	109	x	109
INPUT +	3	-505	-286	109	x	109
V-	4	-384	-519	109	x	109
BALANCE	5	488	-519	109	x	109
OUTPUT	6	61	507	109	x	109
V+	7	-147	507	109	x	109
COMPENSATION	8	-358	507	109	x	109

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